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APPLICATION NO. FILING DA	TE FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
10/575,680 · 04/13/200	06 Yasuhiro Watanabe	0707590043	4618	
20277 7590 MCDERMOTT WILL & EM	01/23/2008 FRY LLP	EXAM	EXAMINER	
600 13TH STREET, N.W. WASHINGTON, DC 20005-3096		ZHANG,	ZHANG, YUANDA	
	3096	ART UNIT	PAPER NUMBER	
		2828		
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		MAIL DATE	DELIVERY MODE	
		01/23/2008	PAPER	

Please find below and/or attached an Office communication concerning this application or proceeding.

The time period for reply, if any, is set in the attached communication.

	Application No.	Applicant(s)			
•	Application No.				
Office Action Commence	10/575,680	WATANABE ET AL.			
Office Action Summary	Examiner	Art Unit			
	Yuanda Zhang	2828			
The MAILING DATE of this communical Period for Reply	tion appears on the cover sheet w	ith the correspondence address			
A SHORTENED STATUTORY PERIOD FOR WHICHEVER IS LONGER, FROM THE MAIL  - Extensions of time may be available under the provisions of 3' after SIX (6) MONTHS from the mailing date of this communic  - If NO period for reply is specified above, the maximum statuto  - Failure to reply within the set or extended period for reply will, Any reply received by the Office later than three months after the earned patent term adjustment. See 37 CFR 1.704(b).	ING DATE OF THIS COMMUNION (CFR 1.136(a)). In no event, however, may a ration.  Ty period will apply and will expire SIX (6) MON by statute, cause the application to become AB	CATION. reply be timely filed ITHS from the mailing date of this communication. BANDONED (35 U.S.C. § 133).			
Status					
1) Responsive to communication(s) filed of	n <u>13 <i>April 2006</i></u> .	·			
2a) This action is <b>FINAL</b> . 2b)	This action is <b>FINAL</b> . 2b)⊠ This action is non-final.				
3) Since this application is in condition for	•	•			
closed in accordance with the practice	under <i>Ex parte Quayle</i> , 1935 C.D	). 11, 453 O.G. 213.			
Disposition of Claims					
4)⊠ Claim(s) <u>1-6</u> is/are pending in the applic	cation.				
4a) Of the above claim(s) is/are v					
5) Claim(s) is/are allowed.					
6)⊠ Claim(s) <u>1-6</u> is/are rejected.					
7) Claim(s) is/are objected to.					
8) Claim(s) are subject to restriction	and/or election requirement.				
Application Papers					
9) The specification is objected to by the E.	xaminer.				
10)⊠ The drawing(s) filed on 13 April 2006 is/		cted to by the Examiner.			
Applicant may not request that any objection	n to the drawing(s) be held in abeyar	nce. See 37 CFR 1.85(a).			
Replacement drawing sheet(s) including the	correction is required if the drawing	(s) is objected to. See 37 CFR 1.121(d).			
11)☐ The oath or declaration is objected to by	the Examiner. Note the attached	d Office Action or form PTO-152.			
Priority under 35 U.S.C. § 119					
12)⊠ Acknowledgment is made of a claim for a)⊠ All b)□ Some * c)□ None of:	foreign priority under 35 U.S.C. §	3 119(a)-(d) or (f).			
1. Certified copies of the priority doc	cuments have been received.	•			
2. Certified copies of the priority doc	cuments have been received in A	pplication No			
<ol><li>Copies of the certified copies of the</li></ol>	•	received in this National Stage			
application from the International	• • • • • • • • • • • • • • • • • • • •				
* See the attached detailed Office action for	r a list of the certified copies not	received.			
Attachment(s)		•			
<ol> <li>Notice of References Cited (PTO-892)</li> <li>Notice of Draftsperson's Patent Drawing Review (PTO-</li> </ol>		Summary (PTO-413) S)/Mail Date			
<ol> <li>Notice of Draftsperson's Patent Drawing Review (PTO-3)</li> <li>Information Disclosure Statement(s) (PTO/SB/08)</li> <li>Paper No(s)/Mail Date 04/13/06:08/24/07:10/09/07</li> </ol>		nformal Patent Application			

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## **DETAILED ACTION**

1. Receipt is acknowledged of papers submitted under 35 U.S.C. 119(a)-(d), which papers have been placed of record in the file.

#### Information Disclosure Statement

2. The information disclosure statement (IDS) submitted on 04/13/06, 08/24/07 and 10/09/07 is being considered by the examiner.

# Claim Rejections - 35 USC § 102

3. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

- (b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.
- 4. Claims 1, 2 and 4 are rejected under 35 U.S.C. 102(b) as being anticipated by Abe (US PG Pub 2002/0021725 A1).
- 5. In re claim 1, Abe discloses a two-beam semiconductor laser device comprising: a two-beam semiconductor element (laser diode 14a, shown in figure 7) having a first and a second semiconductor laser elements (LD 1 and LD2) that can be driven independently and that are formed integrally on a substrate (30); and a submount (13) having, mounted on a front part thereof, the two-beam semiconductor laser element with a light-emitting face (active layer 33 for LD1 and active layer 38 for LD2) thereof directed forward and having a first and a second electrode pads (13a) connected to electrodes of the first and second semiconductor laser element by being kept in contact therewith, wherein the first and second electrode pads are formed to extend farther

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behind the two-beam semiconductor laser element (electrode 13a has been extended behind the laser diode 14a, shown in figure 8A), and are wire-bonded behind the two-beam semiconductor laser element (shown in figure 8A) (paragraph [0131] – paragraph [137]).

- 6. In re claim 2, Abe discloses wherein the first and second electrode pads are wirebonded at a rear end of the submount (see figure 8A).
- 7. In re claim 4, Abe discloses wherein a lateral length of the submount is 400  $\mu$ m or more but 700  $\mu$ m or less (Figure 8B has disclosed that the two emitting point is 100  $\mu$ m apart which is roughly less ½ of the lateral length or width of the submount; therefore, the submount is more than about 400  $\mu$ m).

# Claim Rejections - 35 USC § 103

- 8. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
  - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 9. Claim 3 is rejected under 35 U.S.C. 103(a) as being unpatentable over Abe (US PG Pub 2002/0021725 A1).
- 10. In re claim 3, Abe has disclosed the claimed invention except wherein a distance from the rear end of the two-beam semiconductor laser element to a position where the first and second electrode pads are wire-bonded is 300 µm or shorter. It would have been obvious to one having ordinary skill in the art at the time the invention was made

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to have modified the distance between the electrode pad that are wire-bonded and rear end of the two-bam semiconductor laser element of Abe with a range of 300 µm or less, since it has been held that where the general conditions of a claim are disclosed in the prior art, discovering the optimum or workable ranges involves only routine skill in the art. *In re Aller*, 105 USPQ 233 MPEP 2144.05 (II-A)

- 11. Claims 5 and 6 are rejected under 35 U.S.C. 103(a) as being unpatentable over Abe (US PG Pub 2002/0021725 A1) in view of Honda et al (US Patent 6,885,076 B2).
- 12. In re claim 5, Abe has disclosed the claimed invention above except a package composed of a frame and a resin member. However, Honda et al disclose a semiconductor laser package composed of individual lead leads (lead frame 2) are put together by the insulating resin member (5) as to form a lead frame package (col. 4 lines 19-26). It would have been obvious to one having ordinary skill in the art at the time the invention was made to have modified the semiconductor laser device of Abe with a package composed of a frame and a resin member as taught by Honda et al in order to obtain protection for the laser element.
- 13. In re claim 6, Honda et al disclose wherein the two-beam semiconductor laser device is built as a three-terminal two-beam semiconductor laser device having three terminals (lead frame 2 containing three thermals 7, 6b and 8).

## Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Yuanda Zhang whose telephone number is 571-270-1439. The examiner can normally be reached on Monday-Thursday, 7:30am-6:00p EST.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Minsun Harvey can be reached on 571-272-1835. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free). If you would like assistance from a USPTO Customer Service Representative or access to the automated information system, call 800-786-9199 (IN USA OR CANADA) or 571-272-1000.

YZ 1/17/08

